## **Electronic Components Assembly Materials**

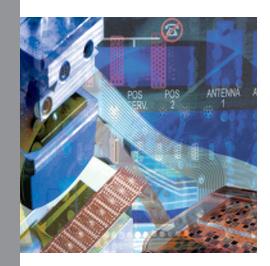
EMI/RFI SH	HELDING OF RIBBO	ON CABLES A	ND FLEX C	RCUITS			
SILVER INKS							
Product #	Sheet Resist (ohms/sq/mi		Application Technique		Comm	Comments	
102-05F	0.019 Scree		en-printable		Flexible	Flexible, temperature and chemical resistant.	
105-43	0.019 Spi		prayable Concentrate		Flexible	Flexible, temperature and chemical resistant.	
117-48	0.040	0.040 Screen-printa		able F		e, temperature and chemical resistant.	
120-07	0.010	Screen	n-printable	Extreme		nely flexible. Can be diluted for spray applying.	
118-41	0.010	Screen	n-printable			ent adhesion to Kapton and other materials where higher temperature is required. ant to abrasion and scratching.	
125-24	0.020	Spraya	Sprayable		Very resistant to abrasion, scratching and flexing. Can be dried at room temperature.		
DIELECTRIC INKS AND COATINGS							
Product #	Dielectric Strength (volts/mil)	Curing Me	thod	Application Technique		Comments	
113-48	525	UV/Therma	al	Screen-print		Very flexible.	
116-20	365	UV		Screen-print		Clear, UV Curable.	
118-12A/B	450	Thermal	ermal Screen-print			Solvent resistant.	
125-17M	365 UV		Screen-print			Matte colorless.	
125-17MB	365 UV		Screen-print			Matte blue.	
125-17MG	365 UV			Screen-print		Matte green.	
POTTING A	ND ENCAPSULATIN	G MATERIALS	;				
ONE COMPONENT SYSTEMS							
Product #	Volume Resistivity (ohms-cm)	Viscosity (cps)	@ 25°C	Viscosity @ 50° (cps)	°C	Comments	
108-50	1 X 10 <sup>14</sup> 100,0		000 - 160,000 30,000 - 50		)	Exceptional resistance to thermal cycling. Low stress, low shrink potting compound and adhesive. Ideal for stress sensitive substrates.	
110-18	1 X 10 <sup>15</sup>	1 X 10 <sup>15</sup> 10,000		60,000		Cures at low temperatures with minimum amount of exotherm, releases air rapidly, resulting in smooth pinhole free surface. Useful for bonding and potting of dissimilar materials requiring Class "B" service temperature rating.	
109-12	1 X 10 <sup>14</sup>	1 X 10 <sup>14</sup> 500,000		60,000		Exceptional resistance to thermal cycling. Bonds dissimilar materials requiring Class "F+" service temperature rating. More thermally conductive version of 108-50.	
TWO COMPONENT SYSTEMS							
Product # Part A		Mix Ratio By Weight	Viscosii (cps)	ty Worki @ <b>21</b> °	ng Life 'C	Comments	
F940A	F940B	100:12	2,750	30 mi	ins.	Black, flame-out, epoxy potting and encapsulating compound. Low viscosity, self deaerating, thermally conductive. Room temperature cure.	
F940A	B-187	100:3	3,000	> 4 ho	ours	Low viscosity with long pot life. Requires mild heat cure.	
F947A	F947B	100:12	5,000	30 mi	ins.	Room temperature, improved heat resistance. Other properties similar to F940A/B.	
F947A	B-187	100:3	7,000	> 4 ho	ours	Excellent heat resistance, extended pot life. Requires mild heat cure.	
102-11A	102-11B	100:12	6,000	30 mi	ins.	Crack resistant, black, flame-out, epoxy compound. Room temperature cure, improved resistance to thermal cycling. Other properties similar to F947A/B.	
102-11A	B-187	100:3	7,000	> 4 ho	ours	Excellent resistance to thermal shock, longer pot life. Requires mild heat cure.	
102-12A	102-12B	100:9	15,000	30 mi	ins.	Thermal cycle resistant, black, epoxy compound. Room temperature cure, improved crack resistance. High thermal conductivity.	
102-12A	B-187	100:2.5	16,000	> 4 ho	ours	Same as above, but extended pot life; better resistance to thermal cracking.	
113-33A	113-33B	100:15	380,000	> 30 ı	mins.	Crack resistant, black, flame-out, glob top epoxy. Non sag encapsulant.	

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